- Can Be Used as a 4-Bit Digital Comparator
- Input Clamping Diodes Simplify System Design
- Fully Compatible with Most TTL Circuits

FUNCTION TABLE

| INP | UTS | OUTPUT |
|-----|-----|--------|
| Α | В | Y |
| L | L | н |
| L | н | L |
| н | L. | L |
| н | Н | н |

H = high level, L = low level

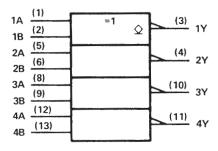
description

The 'LS266 is comprised of four independent 2-input exclusive-NOR gates with open-collector outputs. The open-collector outputs permit tying outputs together for multiple-bit comparisons.

logic symbol (each gate)



logic symbol†



positive logic: $Y = \overline{A \oplus B} = AB + \overline{AB}$

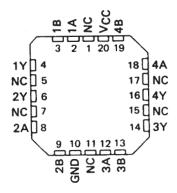
Pin numbers shown are for D, J, N, and W packages.

SN54LS266 . . . J OR W PACKAGE SN74LS266 . . . D OR N PACKAGE (TOP VIEW)

1A 1 U 14 VCC 1B 2 13 4B 1Y 3 12 4A

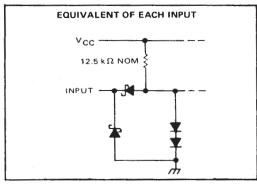
1Y | 3 | 12 | 4A 2Y | 4 | 11 | 4Y 2A | 5 | 10 | 3Y 2B | 6 | 9 | 3B GND | 7 | 8 | 3A

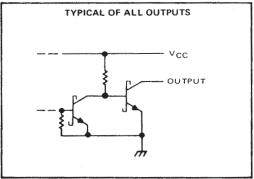
SN54LS266 ... FK PACKAGE (TOP VIEW)



NC - No internal connection

schematic of inputs and outputs







 $^{^{\}dagger}$ This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

SN54LS266, SN74LS266 QUADRUPLE 2-INPUT EXCLUSIVE-NOR GATES WITH OPEN-COLLECTOR OUTPUTS

SDLS151 - DECEMBER 1972 - REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

| Supply voltage, VCC (see Note 1) | | | | | | | | | | | | | | 7 | ٧ |
|---------------------------------------|-----------|--|----|--|--|--|--|--|--|--|---|-----|------|--------|----|
| Input voltage | | | | | | | | | | | | | | 7 | ٧ |
| Operating free-air temperature range: | SN54LS266 | | ٠. | | | | | | | | Ę | 55° | C to | 125 | °C |
| | SN74LS266 | | | | | | | | | | | 0 | °C | to 70' | °C |
| Storage temperature range | | | | | | | | | | | | | | 150 | |

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

| | SI | V54LS2 | 66 | SI | UNIT | | |
|--|-----|--------|-----|------|------|------|-----|
| | MIN | NOM | MAX | MIN | NOM | MAX | ONT |
| Supply voltage, V _{CC} | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | ٧ |
| High-level output voltage, VOH | | | 5.5 | | | 5.5 | ٧ |
| Low-level output current, IOL | | | 4 | | | 8 | mA |
| Operating free-air temperature, T _A | -55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | 7507.004 | SI | N54LS2 | 66 | S | UNIT | | | |
|-----------|--|--|---|------------------|------|------|------|------|------|----|
| | PAHAMETER | TEST CON | MIN | TYP [‡] | MAX | MIN | TYP‡ | MAX | ONT | |
| VIH | High-level input voltage | | | 2 | | | 2 | | | ٧ |
| VIL | Low-level input voltage | | | | | 0.7 | | | 0.8 | V |
| VIK | Input clamp voltage | VCC = MIN, | I _I = -18 mA | | | 1.5 | | | -1.5 | ٧ |
| ЮН | High-level output current | V _{CC} = MIN, V _{IL} = V _{IL} max, | V _{IH} = 2 V, V _{OH} = 5.5 V | | | 100 | | | 100 | μА |
| VOL | Low-level output voltage | V _{CC} ≈ MIN, V _{IH} = 2 V, | IOL = 4 mA | | 0.25 | 0.4 | | 0.25 | 0.4 | V |
| VOL | Low-level output voltage | VIL = VIL max | I _{OL} = 8 mA | | | | | 0.35 | 0.5 | |
| - la | Input current at maximum input voltage | V _{CC} = MAX, | V1 = 7 V | | | 0.2 | | | 0.2 | mA |
| ЧН | High-level input current | V _{CC} = MAX, | V ₁ = 2.7 V | | | 40 | | | 40 | μА |
| IL | Low-level input current | V _{CC} = MAX, | V ₁ = 0.4 V | | | -0.8 | | | -0.8 | mA |
| Icc | Supply current | V _{CC} = MAX, | See Note 2 | | 8 | 13 | | 8 | 13 | mA |

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. ‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_{A} = 25 \text{ C}$.

switching characteristics, VCC = 5 V, TA = 25°C

| PARAMETER [§] | FROM (INPUT) | TEST CO | NDITIONS | MIN | TYP | MAX | UNIT |
|------------------------|-----------------|------------------|---------------------|-----|-----|-----|------|
| ^t PLH | A or B | Other input low | CL = 15 pF, | | 18 | 30 | ns |
| tPHL | 7015 | Other mpat low | $R_L = 2 k\Omega$, | | 18 | 30 | 113 |
| t _{PLH} | A or B | Other input high | See Note 3 | | 18 | 30 | ns |
| tPHL | 7, 0, 0 | Other input high | 00011010 | | 18 | 30 | |

[§]tpLH = propagation delay time, low-to-high-level output



NOTE 2: 1_{CC} is measured with one input of each gate at 4.5 V, the other inputs grounded, and the outputs open

tpHL = propagation delay time, high-to-low-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

www.ti.com 13-Aug-2021

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|------------|--------------|--------------------|------|----------------|---------------------|-------------------------------|--------------------|--------------|-------------------------|---------|
| SN54LS266J | ACTIVE | CDIP | J | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | SN54LS266J | Samples |
| SN74LS266D | ACTIVE | SOIC | D | 14 | 50 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS266 | Samples |
| SN74LS266DG4 | ACTIVE | SOIC | D | 14 | 50 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS266 | Samples |
| SN74LS266N | ACTIVE | PDIP | N | 14 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74LS266N | Samples |
| SNJ54LS266J | ACTIVE | CDIP | J | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | SNJ54LS266J | Samples |
| SNJ54LS266W | ACTIVE | CFP | W | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | SNJ54LS266W | Samples |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

PACKAGE OPTION ADDENDUM

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS266, SN74LS266:

Catalog: SN74LS266

Military: SN54LS266

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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